# DALLAS

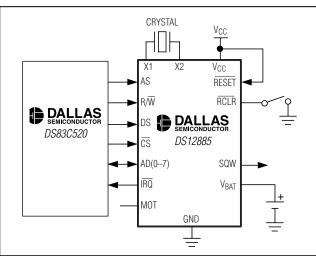
# **Real-Time Clock**

### **General Description**

The DS12885, DS12887, and DS12C887 real-time clocks (RTCs) are designed to be direct replacements for the DS1285 and DS1287. The devices provide a real-time clock/calendar, one time-of-day alarm, three maskable interrupts with a common interrupt output, a programmable square wave, and 114 bytes of batterybacked static RAM (113 bytes in the DS12C887 and DS12C887A). The DS12887 integrates a quartz crystal and lithium energy source into a 24-pin encapsulated DIP package. The DS12C887 adds a century byte at address 32h. For all devices, the date at the end of the month is automatically adjusted for months with fewer than 31 days, including correction for leap years. The devices also operate in either 24-hour or 12-hour format with an AM/PM indicator. A precision temperature-compensated circuit monitors the status of V<sub>CC</sub>. If a primary power failure is detected, the device automatically switches to a backup supply. A lithium coin-cell battery can be connected to the VBAT input pin on the DS12885 to maintain time and date operation when primary power is absent. The device is accessed through a multiplexed byte-wide interface, which supports both Intel and Motorola modes.

### **Applications**

**Embedded Systems** Utility Meters Security Systems Network Hubs, Bridges, and Routers



# Typical Operating Circuit

Pin Configurations and Ordering Information appear at end of data sheet.

# 

Maxim Integrated Products 1

For pricing, delivery, and ordering information, please contact Maxim/Dallas Direct! at 1-888-629-4642, or visit Maxim's website at www.maxim-ic.com.

#### Features

- Drop-In Replacement for IBM AT Computer Clock/Calendar
- RTC Counts Seconds, Minutes, Hours, Day, Date, Month, and Year with Leap Year Compensation Through 2099
- Binary or BCD Time Representation
- ♦ 12-Hour or 24-Hour Clock with AM and PM in 12-Hour Mode
- Daylight Saving Time Option
- Selectable Intel or Motorola Bus Timing
- Interfaced with Software as 128 RAM Locations
- 14 Bytes of Clock and Control Registers
- ♦ 114 Bytes of General-Purpose, Battery-Backed RAM (113 Bytes in the DS12C887 and DS12C887A)
- RAM Clear Function (DS12885, DS12887A, and DS12C887A)
- Interrupt Output with Three Independently Maskable Interrupt Flags
- Time-of-Day Alarm Once Per Second to Once Per Day
- Periodic Rates from 122µs to 500ms
- End-of-Clock Update Cycle Flag
- Programmable Square-Wave Output
- Automatic Power-Fail Detect and Switch Circuitry
- Optional 28-Pin PLCC Surface Mount Package or 32-Pin TQFP (DS12885)
- Optional Encapsulated DIP (EDIP) Package with Integrated Crystal and Battery (DS12887, DS12887A, DS12C887, DS12C887A)
- Optional Industrial Temperature Range Available
- Underwriters Laboratory (UL) Recognized

#### **ABSOLUTE MAXIMUM RATINGS**

Voltage Range on V <sub>CC</sub> Pin Rela	tive to Ground0.3V to +6.0V
Operating Temperature Range	
Commercial (noncondensing)	0°C to +70°C
Operating Temperature Range	
Industrial (noncondensing)	40°C to +85°C

Storage Temperature Range	55°C to +125°C
Soldering Temperature	See IPC/JEDEC
	J-STD-020 Specification (Note 1)
Soldering Temperature (leads	, 10s)+260°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

#### **DC ELECTRICAL CHARACTERISTICS**

(Vcc = +4.5V to +5.5V, T<sub>A</sub> = over the operating range, unless otherwise noted.) (Note 2)

PARAMETER	SYMBOL	CONDITIONS	MIN	ТҮР	МАХ	UNITS
Supply Voltage	Vcc	(Note 3)	4.5		5.5	V
V <sub>BAT</sub> Input Voltage	VBAT	(Note 3)	2.5		4.0	V
Input Logic 1	VIH	(Note 3)	2.2		V <sub>CC</sub> + 0.3	V
Input Logic 0	VIL	(Note 3)	-0.3		+0.8	V
V <sub>CC</sub> Power-Supply Current	ICC1	(Note 4)			15	mA
V <sub>CC</sub> Standby Current	Iccs	(Note 5)				mA
Input Leakage	١ <sub>١</sub> ٢		-1.0		+1.0	μA
I/O Leakage	IOL	(Note 6)	-1.0		+1.0	μA
Input Current	IMOT	(Note 7)	-1.0		+500	μA
Output at 2.4V	ЮН	(Note 3)	-1.0			mA
Output at 0.4V	IOL	(Note 3)			4.0	mA
Power-Fail Voltage	VPF	(Note 3)	4.0	4.25	4.5	V
VRT Trip Point	VRT <sub>TRIP</sub>			1.3		V

DALLAS /////

#### DC ELECTRICAL CHARACTERISTICS

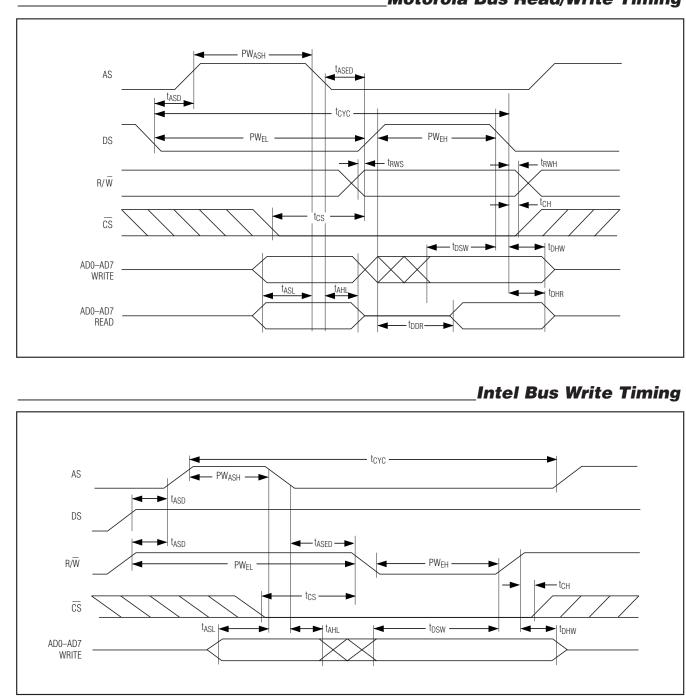
 $(V_{CC} = 0V, V_{BAT} = 3.0V, T_A = over the operating range, unless otherwise noted.) (Note 2)$ 

PARAMETER	SYMBOL	CONDITIONS	MIN	ТҮР	MAX	UNITS
$V_{BAT}$ Current (OSC On); T <sub>A</sub> = +25°C, V <sub>BACKUP</sub> = 3.0V	IBAT	(Note 8)			500	nA
VBAT Current (Oscillator Off)	IBATDR	(Note 8)			100	nA

### **AC ELECTRICAL CHARACTERISTICS**

 $(\textbf{V_{CC}} = \textbf{4.5V to 5.5V}, \, \textbf{T}_{A} = \text{over the operating range.}) \, (\text{Note 2})$ 

PARAMETER	SYMBOL	CONDITIONS	MIN	ТҮР	MAX	UNITS
Cycle Time	tcyc		385		DC	ns
Pulse Width, DS Low or R/W High	PWEL		150			ns
Pulse Width, DS High or $R/\overline{W}$ Low	PWEH		125			ns
Input Rise and Fall	t <sub>R</sub> , t <sub>F</sub>				30	ns
R/W Hold Time	t <sub>RWH</sub>		10			ns
R/W Setup Time Before DS/E	trws		50			ns
Chip-Select Setup Time Before DS or $R/\overline{W}$	tcs		20			ns
Chip-Select Hold Time	tсн		0			ns
Read-Data Hold Time	<sup>t</sup> DHR		10		80	ns
Write-Data Hold Time	tdhw		0			ns
Address Valid Time to AS Fall	tasl		30			ns
Address Hold Time to AS Fall	tahl		10			ns
Delay Time DS/E to AS Rise	tasd		20			ns
Pulse Width AS High	PWASH		60			ns
Delay Time, AS to DS/E Rise	<b>t</b> ASED		40			ns
Output Data Delay Time from DS or $R/\overline{W}$	<sup>t</sup> DDR		20		120	ns
Data Setup Time	t <sub>DSW</sub>		100			ns
Reset Pulse Width	t <sub>RWL</sub>		5			μs
IRQ Release from DS	t <sub>IRDS</sub>				2	μs
IRQ Release from RESET	t <sub>IRR</sub>				2	μs

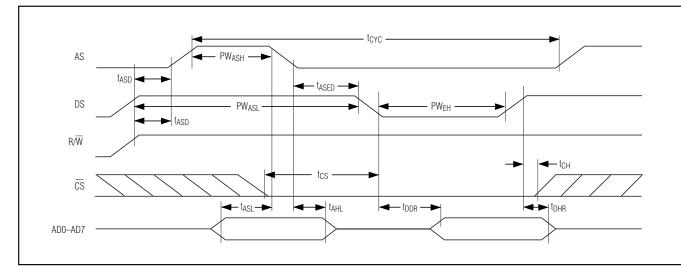


Motorola Bus Read/Write Timing

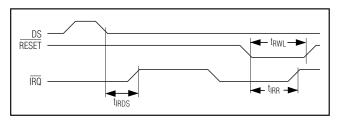
DS12885/DS12887/DS12887A/DS12C887/DS12C887A



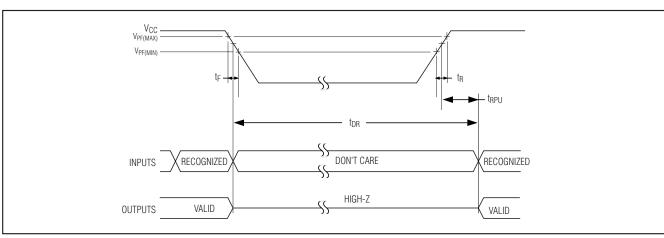
#### \_Intel Bus Read Timing



**IRQ** Release Delay Timing



Power-Up/Power-Down Timing



### **POWER-UP/POWER-DOWN CHARACTERISTICS**

 $(T_A = -40^{\circ}C \text{ to } +85^{\circ}C) \text{ (Note 2)}$ 

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Recovery at Power-Up	t <sub>RPU</sub>		20		200	ms
V <sub>CC</sub> Fall Time; V <sub>PF(MAX)</sub> to V <sub>PF(MIN)</sub>	tF		300			μs
V <sub>CC</sub> Rise Time; V <sub>PF(MIN)</sub> to V <sub>PF(MAX)</sub>	t <sub>R</sub>		0			μs

### DATA RETENTION

 $(T_A = +25^{\circ}C)$ 

PARAMETER	SYMBOL	CONDITIONS	MIN	ТҮР	МАХ	UNITS
Expected Data Retention	t <sub>DR</sub>		10			years

### CAPACITANCE

 $(T_A = +25^{\circ}C)$  (Note 9)

PARAMETER	SYMBOL	CONDITIONS	MIN	ТҮР	MAX	UNITS
Capacitance on All Input Pins Except X1 and X2	C <sub>IN</sub>				5	pF
Capacitance on IRQ, SQW, and DQ Pins	C <sub>IO</sub>				7	pF

### AC TEST CONDITIONS

PARAMETER	TEST CONDITIONS
Input Pulse Levels	0 to 3.0V
Output Load Including Scope and Jig	50pF + 1TTL Gate
Input and Output Timing Measurement Reference Levels	Input/Output: VIL maximum and VIH minimum
Input-Pulse Rise and Fall Times	5ns

#### WARNING: Negative undershoots below -0.3V while the part is in battery-backed mode may cause loss of data.

Note 1: RTC modules can be successfully processed through conventional wave-soldering techniques as long as temperature exposure to the lithium energy source contained within does not exceed +85°C. However, post-solder cleaning with waterwashing techniques is acceptable, provided that ultrasonic vibrations are not used to prevent crystal damage.
Note 2: Limits at -40°C are guaranteed by design and not production tested.

**Note 3:** All voltages are referenced to ground.

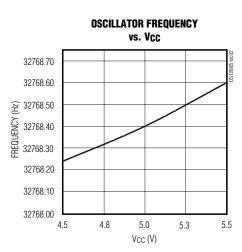
**Note 4:** All outputs are open.

**Note 5:** Specified with  $\overline{CS} = DS = R/\overline{W} = \overline{RESET} = V_{CC}$ ; MOT, AS, AD0–AD7 = 0;  $V_{BACKUP}$  open.

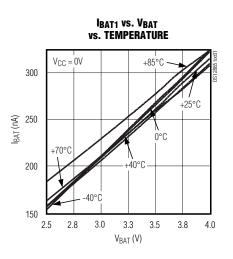
- Note 6: Applies to the AD0 to AD7 pins, the IRQ pin, and the SQW pin when each is in a high-impedance state.
- Note 7: The MOT pin has an internal  $20k\Omega$  pulldown.
- Note 8: Measured with a 32.768kHz crystal attached to X1 and X2.
- Note 9: Guaranteed by design. Not production tested.

Note 10: Measured with a 50pF capacitance load.

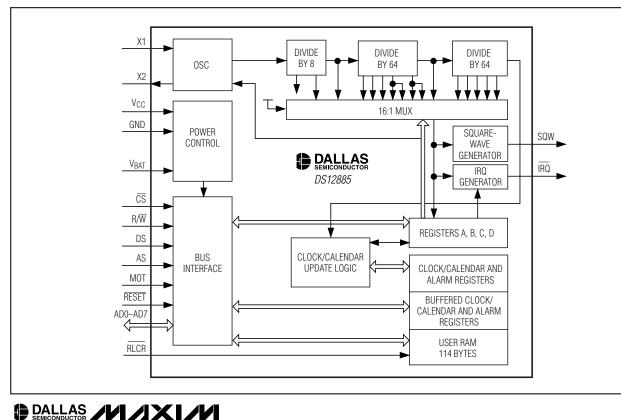
## **Typical Operating Characteristics**



(V<sub>CC</sub> = +5.0V,  $T_A$  = +25°C, unless otherwise noted.)



### Functional Diagram



DS12885/DS12887/DS12887A/DS12C887/DS12C887A

#### PIN SO, NAME FUNCTION EDIP PLCC TQFP PDIP Motorola or Intel Bus Timing Selector. This pin selects one of two bus types. When connected to V<sub>CC</sub>, Motorola bus timing is selected. When connected to GND or 1 1 2 29 MOT left disconnected, Intel bus timing is selected. The pin has an internal pulldown resistor Connections for Standard 32.768kHz Quartz Crystal. The internal oscillator 2 3 30 X1 circuitry is designed for operation with a crystal having a 6pF specified load capacitance (C<sub>I</sub>). Pin X1 is the input to the oscillator and can optionally be connected to an external 32.768kHz oscillator. The output of the internal oscillator, 3 4 31 Х2 pin X2, is floated if an external oscillator is connected to pin X1. Multiplexed, Bidirectional Address/Data Bus. The addresses are presented during the first portion of the bus cycle and latched into the device by the falling edge of AS. Write data is latched by the falling edge of DS (Motorola timing) or the rising 1, 2, 3, AD0-5-10, edge of R/W (Intel timing). In a read cycle, the device outputs data during the 4-11 4-11 5, 7, 8, 12, 14 AD7 latter portion of DS (DS and R/W high for Motorola timing, DS low and R/W high for 9, 11 Intel timing). The read cycle is terminated and the bus returns to a highimpedance state as DS transitions low in the case of Motorola timing or as DS transitions high in the case of Intel timing. 12, 16 12 15, 20 12, 17 GND Ground Active-Low Chip-Select Input. The chip-select signal must be asserted low for a bus cycle in the device to be accessed. CS must be kept in the active state during DS and AS for Motorola timing and during DS and R/W for Intel timing. Bus cycles $\overline{\text{CS}}$ 13 13 16 13 that take place without asserting $\overline{CS}$ will latch addresses, but no access occurs. When V<sub>CC</sub> is below V<sub>PF</sub> volts, the device inhibits access by internally disabling the CS input. This action protects the RTC data and the RAM data during power outages. Address Strobe Input. A positive-going address-strobe pulse serves to demultiplex the bus. The falling edge of AS causes the address to be latched within the device. The next rising edge that occurs on the AS bus clears the 14 14 17 14 AS address regardless of whether $\overline{\text{CS}}$ is asserted. An address strobe must immediately precede each write or read access. If a write or read is performed with $\overline{CS}$ deasserted, another address strobe must be performed prior to a read or write access with $\overline{\text{CS}}$ asserted. Read/Write Input. The R/W pin has two modes of operation. When the MOT pin is connected to $V_{CC}$ for Motorola timing, R/W is at a level that indicates whether the current cycle is a read or write. A read cycle is indicated with a high level on R/WR/W 15 while DS is high. A write cycle is indicated when R/W is low during DS. When the 15 19 16 MOT pin is connected to GND for Intel timing, the R/W signal is an active-low signal. In this mode, the R/W pin operates in a similar fashion as the write-enable signal (WE) on generic RAMs. Data are latched on the rising edge of the signal.

**Pin Description** 

## Pin Description (continued)

	P	IN			
SO, PDIP	EDIP	PLCC	TQFP	NAME	FUNCTION
22	2, 3, 16, 20, 21, 22	1, 11, 13, 18, 26	4, 6, 10, 15, 20, 23, 25, 27, 32	N.C.	No Connection. This pin should remain unconnected. Pin 21 is $\overline{\text{RCLR}}$ for the DS12887A/DS12C887A. On the EDIP, these pins are missing by design.
17	17	21	18	DS	Data Strobe or Read Input. The DS pin has two modes of operation depending on the level of the MOT pin. When the MOT pin is connected to $V_{CC}$ , Motorola bus timing is selected. In this mode, DS is a positive pulse during the latter portion of the bus cycle and is called data strobe. During read cycles, DS signifies the time that the device is to drive the bidirectional bus. In write cycles, the trailing edge of DS causes the device to latch the written data. When the MOT pin is connected to GND, Intel bus timing is selected. DS identifies the time period when the device drives the bus with read data. In this mode, the DS pin operates in a similar fashion as the output-enable ( $\overline{OE}$ ) signal on a generic RAM.
18	18	22	19	RESET	Active-Low Reset Input. The RESET pin has no effect on the clock, calendar, or RAM. On power-up, the RESET pin can be held low for a time to allow the power supply to stabilize. The amount of time that RESET is held low is dependent on the application. However, if RESET is used on power-up, the time RESET is low should exceed 200ms to ensure that the internal timer that controls the device on power- up has timed out. When RESET is low and V <sub>CC</sub> is above V <sub>PF</sub> , the following occurs: A. Periodic interrupt-enable (PIE) bit is cleared to 0. B. Alarm interrupt-enable (AIE) bit is cleared to 0. C. Update-ended interrupt-enable (UIE) bit is cleared to 0. D. Periodic-interrupt flag (PF) bit is cleared to 0. E. Alarm-interrupt flag (AF) bit is cleared to 0. G. Interrupt-request status flag (IRQF) bit is cleared to 0. H. IRQ pin is in the high-impedance state. I. The device is not accessible until RESET is returned high. J. Square-wave output-enable (SQWE) bit is cleared to 0. In a typical application, RESET can be connected to V <sub>CC</sub> . This connection allows the device to go in and out of power fail without affecting any of the control registers.

### DALLAS /////

## Pin Description (continued)

	PIN							
SO, PDIP	EDIP	PLCC	TQFP	NAME	FUNCTION			
19	19	23	21	ĪRQ	Active-Low Interrupt Request Output. The $\overline{IRQ}$ pin is an active-low output of the device that can be used as an interrupt input to a processor. The $\overline{IRQ}$ output remains low as long as the status bit causing the interrupt is present and the corresponding interrupt-enable bit is set. The processor program normally reads the C register to clear the $\overline{IRQ}$ pin. The $\overline{RESET}$ pin also clears pending interrupts. When no interrupt conditions are present, the $\overline{IRQ}$ level is in the high-impedance state. Multiple interrupting devices can be connected to an $\overline{IRQ}$ bus, provided that they are all open drain. The $\overline{IRQ}$ pin is an open-drain output and requires an external pullup resistor to $V_{CC}$ .			
20		24	22	VBAT	Connection for a Primary Battery. (DS12885 Only.) Battery voltage must be held between the minimum and maximum limits for proper operation. If a backup supply is not supplied, $V_{BAT}$ must be grounded. Connect the battery directly to the $V_{BAT}$ pin. Diodes in series between the $V_{BAT}$ pin and the battery may prevent proper operation. UL recognized to ensure against reverse charging when used with a lithium battery.			
21	21 (DS12887A/ DS12C887A)	25	24	RCLR	Active-Low RAM Clear. The $\overline{\text{RCLR}}$ pin is used to clear (set to logic 1) all the general-purpose RAM, but does not affect the RAM associated with the RTC. To clear the RAM, $\overline{\text{RCLR}}$ must be forced to an input logic 0 during battery-backup mode when V <sub>CC</sub> is not applied. The $\overline{\text{RCLR}}$ function is designed to be used through a human interface (shorting to ground manually or by a switch) and not to be driven with external buffers. This pin is internally pulled up. Do not use an external pullup resistor on this pin.			
23	23	27	26	SQW	Square-Wave Output. The SQW pin can output a signal from one of 13 taps provided by the 15 internal divider stages of the RTC. The frequency of the SQW pin can be changed by programming Register A, as shown in Table 1. The SQW signal can be turned on and off using the SQWE bit in Register B. The SQW signal is not available when $V_{CC}$ is less than $V_{PF}$ .			
24	24	28	28	V <sub>CC</sub>	DC Power Pin for Primary Power Supply. When $V_{CC}$ is applied within normal limits, the device is fully accessible and data can be written and read. When $V_{CC}$ is below $V_{PF}$ reads and writes are inhibited.			

### **Detailed Description**

The DS12885 family of RTCs provide 14 bytes of realtime clock/calendar, alarm, and control/status registers and 114 bytes (113 bytes for DS12C887 and DS12C887A) of nonvolatile, battery-backed static RAM. A time-of-day alarm, three maskable interrupts with a common interrupt output, and a programmable squarewave output are available. The devices also operate in either 24-hour or 12-hour format with an AM/PM indicator. A precision temperature-compensated circuit monitors the status of V<sub>CC</sub>. If a primary power-supply failure is detected, the devices automatically switch to a backup supply. The backup supply input supports a primary battery, such as lithium coin cell. The devices are accessed through a multiplexed address/data bus that supports Intel and Motorola modes.

#### **Oscillator Circuit**

The DS12885 uses an external 32.768kHz crystal. The oscillator circuit does not require any external resistors or capacitors to operate. Table 1 specifies several crystal parameters for the external crystal. Figure 1 shows a functional schematic of the oscillator circuit. An enable bit in the control register controls the oscillator. Oscillator startup times are highly dependent upon crystal characteristics, PC board leakage, and layout. High ESR and excessive capacitive loads are the major contributors to long startup times. A circuit using a crystal with the recommended characteristics and proper layout usually starts within one second.

An external 32.768kHz oscillator can also drive the DS12885. In this configuration, the X1 pin is connected to the external oscillator signal and the X2 pin is floated.

#### Table 1. Crystal Specifications\*

PARAMETER	SYMBOL	MIN	ТҮР	MAX	UNITS
Nominal Frequency	fO		32.768		kHz
Series Resistance	ESR			50	kΩ
Load Capacitance	CL		6		pF

\*The crystal, traces, and crystal input pins should be isolated from RF generating signals. Refer to Application Note 58: Crystal Considerations for Dallas Real-Time Clocks for additional specifications.

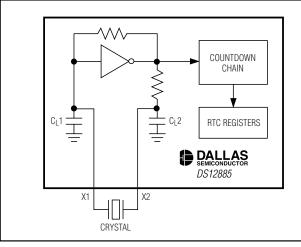


Figure 1. Oscillator Circuit Showing Internal Bias Network

### DALLAS JUI JXIJUI

DS12885/DS12887/DS12887A/DS12C887/DS12C887A

#### **Clock Accuracy**

The accuracy of the clock is dependent upon the accuracy of the crystal and the accuracy of the match between the capacitive load of the oscillator circuit and the capacitive load for which the crystal was trimmed. Additional error is added by crystal frequency drift caused by temperature shifts. External circuit noise coupled into the oscillator circuit can result in the clock running fast. Figure 2 shows a typical PC board layout for isolation of the crystal and oscillator from noise. Refer to *Application Note 58: Crystal Considerations with Dallas Real-Time Clocks* for more detailed information.

#### Clock Accuracy for DS12887, DS12887A, DS12C887, DS12C887A Only

The encapsulated DIP modules are trimmed at the factory to an accuracy of  $\pm 1$  minute per month at  $\pm 25^{\circ}$ C.

#### Power-Down/Power-Up \_\_\_\_\_Considerations

The real-time clock continues to operate, and the RAM, time, calendar, and alarm memory locations remain nonvolatile regardless of the V<sub>CC</sub> input level. V<sub>BAT</sub> must remain within the minimum and maximum limits when V<sub>CC</sub> is not applied. When V<sub>CC</sub> is applied and exceeds V<sub>PF</sub> (power-fail trip point), the device becomes accessible after t<sub>REC</sub>—if the oscillator is running and the oscillator countdown chain is not in reset (Register A). This time allows the system to stablize after power is applied. If the oscillator is not enabled, the oscillator-enable bit is enabled on power-up, and the device becomes immediately accessible.

#### Time, Calendar, and Alarm Locations

The time and calendar information is obtained by reading the appropriate register bytes. The time, calendar, and alarm are set or initialized by writing the appropriate register bytes. Invalid time or date entries result in undefined operation. The contents of the 10 time, calendar, and alarm bytes can be either binary or binarycoded decimal (BCD) format.

The day-of-week register increments at midnight, incrementing from 1 through 7. The day-of-week register is used by the daylight saving function, so the value 1 is defined as Sunday. The date at the end of the month is

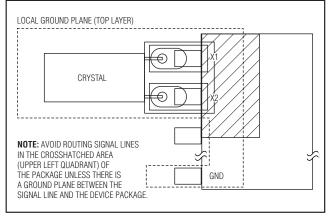


Figure 2. Layout Example

automatically adjusted for months with fewer than 31 days, including correction for leap years.

Before writing the internal time, calendar, and alarm registers, the SET bit in Register B should be written to logic 1 to prevent updates from occurring while access is being attempted. In addition to writing the 10 time, calendar, and alarm registers in a selected format (binary or BCD), the data mode bit (DM) of Register B must be set to the appropriate logic level. All 10 time, calendar, and alarm bytes must use the same data mode. The SET bit in Register B should be cleared after the data mode bit has been written to allow the RTC to update the time and calendar bytes. Once initialized, the RTC makes all updates in the selected mode. The data mode cannot be changed without reinitializing the 10 data bytes. Tables 2A and 2B show the BCD and binary formats of the time, calendar, and alarm locations.

The 24-12 bit cannot be changed without reinitializing the hour locations. When the 12-hour format is selected, the higher-order bit of the hours byte represents PM when it is logic 1. The time, calendar, and alarm bytes are always accessible because they are double-buffered. Once per second the seven bytes are advanced by one second and checked for an alarm condition.

If a read of the time and calendar data occurs during an update, a problem exists where seconds, minutes, hours, etc., may not correlate. The probability of reading incorrect time and calendar data is low. Several methods of avoiding any possible incorrect time and calendar reads are covered later in this text.

The three alarm bytes can be used in two ways. First, when the alarm time is written in the appropriate hours, minutes, and seconds alarm locations, the alarm interrupt is initiated at the specified time each day, if the alarm-enable bit is high. In this mode, the "0" bits in the alarm registers and the corresponding time registers must always be written to 0 (Table 2A and 2B). Writing the 0 bits in the alarm and/or time registers to 1 can result in undefined operation.

The second use condition is to insert a "don't care" state in one or more of the three alarm bytes. The don't-care code is any hexadecimal value from C0 to FF. The two most significant bits of each byte set the don't-care

condition when at logic 1. An alarm is generated each hour when the don't-care bits are set in the hours byte. Similarly, an alarm is generated every minute with don't-care codes in the hours and minute alarm bytes. The don't-care codes in all three alarm bytes create an interrupt every second.

All 128 bytes can be directly written or read, except for the following:

- 1) Registers C and D are read-only.
- 2) Bit 7 of register A is read-only.
- 3) The MSB of the seconds byte is read-only.

	,	1	, 						、 <i>,</i>	
ADDRESS	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0	FUNCTION	RANGE
00H	0		10 Seco	nds		Seco	nds		Seconds	00–59
01H	0		10 Seco	nds		Seco	nds		Seconds Alarm	00–59
02H	0		10 Minu	utes		Minu	ites		Minutes	00–59
03H	0		10 Minu	ites	Minutes				Minutes Alarm	00–59
0.411	AM/PM	0	0	10 Hours		1.1			Lisuna	1–12 +AM/PM
04H	0	0	10	Hours		Ηοι	irs		Hours	00–23
0511	AM/PM	0	0	10 Hours						1–12 +AM/PM
05H	0	0	10	Hours		HOL	Hours		Hours Alarm	00–23
06H	0	0	0	0	0 Day		Day	01–07		
07H	0	0	1(	) Date	Date		Date	01–31		
08H	0	0	0	10 Months		Mor	nth		Month	01–12
09H		10	Years			Yea	ar		Year	00–99
0AH	UIP	DV2	DV1	DV0	RS3	RS2	RS1	RS0	Control	—
0BH	SET	PIE	AIE	UIE	SQWE	DM	24/12	DSE	Control	—
0CH	IRQF	PF	AF	UF	0	0	0	0	Control	_
0DH	VRT	0	0	0	0	0	0	0	Control	—
0EH-31H	Х	Х	Х	Х	Х	Х	Х	Х	RAM	_
32H		10 C	Century			Cent	ury		Century*	00–99
33H-7FH	Х	Х	Х	Х	Х	Х	Х	Х	RAM	_

Table 2A. Time, Calendar, and Alarm Data Modes-BCD Mode (DM = 0)

X = Read/Write Bit.

\*DS12C887, DS12C887A only. General-purpose RAM on DS12885, DS12887, and DS12887A.

**Note:** Unless otherwise specified, the state of the registers is not defined when power is first applied. Except for the seconds register, 0 bits in the time and date registers can be written to 1, but may be modified when the clock updates. 0 bits should always be written to 0 except for alarm mask bits.



#### Table 2B. Time, Calendar, and Alarm Data Modes—Binary Mode (DM = 1)

	DIT 7					DITO			FUNCTION	DANCE	
ADDRESS	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0	FUNCTION	RANGE	
00H	0	0			Second				Seconds	00–3B	
01H	0	0		Seconds			Seconds Alarm	00–3B			
02H	0	0		Minutes			Minutes	00–3B			
03H	0	0			Minute	S			Minutes Alarm	00–3B	
0411	AM/PM	0	0	0		Ηοι	irs		Houro	01–0C +AM/PM	
04H	0	0	0		F	lours			Hours	00–17	
05H	AM/PM	0	0	0		Ηοι	irs		Hours Alarm	01–0C +AM/PM	
0311	0	0			F	lours			Hours Alarm	00–17	
06H	0	0	0	0	0		C	)ay	Day	01–07	
07H	0	0	0		[	Date			Date	01–1F	
08H	0	0	0	0		Mor	nth		Month	01–0C	
09H	0				Year	-			Year	00–63	
0AH	UIP	DV2	DV1	DV0	RS3	RS2	RS1	RS0	Control	—	
0BH	SET	PIE	AIE	UIE	SQWE	DM	24/12	DSE	Control	_	
0CH	IRQF	PF	AF	UF	0	0	0	0	Control		
0DH	VRT	0	0	0	0	0	0	0	Control		
0EH-31H	Х	Х	Х	Х	Х	Х	Х	Х	RAM		
32H		1	N/A			N//	4		Century*		
33H-7FH	Х	Х	Х	Х	Х	Х	Х	Х	RAM	_	

X = Read/Write Bit.

\*DS12C887, DS12C887A only. General-purpose RAM on DS12885, DS12887, and DS12887A.

**Note:** Unless otherwise specified, the state of the registers is not defined when power is first applied. Except for the seconds register, 0 bits in the time and date registers can be written to 1, but may be modified when the clock updates. 0 bits should always be written to 0 except for alarm mask bits.

#### **Control Registers**

The real-time clocks have four control registers that are accessible at all times, even during the update cycle.

MSB

#### **Control Register A**

LSB

BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0
UIP	DV2	DV1	DV0	RS3	RS2	RS1	RS0

**Bit 7: Update-In-Progress (UIP).** This bit is a status flag that can be monitored. When the UIP bit is a 1, the update transfer occurs soon. When UIP is a 0, the update transfer does not occur for at least 244µs. The time, calendar, and alarm information in RAM is fully available for access when the UIP bit is 0. The UIP bit is read-only and is not affected by RESET. Writing the SET bit in Register B to a 1 inhibits any update transfer and clears the UIP status bit.

**Bits 6, 5, and 4: DV2, DV1, DV0.** These three bits are used to turn the oscillator on or off and to reset the countdown chain. A pattern of 010 is the only combination of bits that turn the oscillator on and allow the RTC to keep time. A pattern of 11x enables the oscillator but holds the countdown chain in reset. The next update occurs at 500ms after a pattern of 010 is written to DV0, DV1, and DV2.

**Bits 3 to 0: Rate Selector (RS3, RS2, RS1, RS0).** These four rate-selection bits select one of the 13 taps on the 15-stage divider or disable the divider output. The tap selected can be used to generate an output square wave (SQW pin) and/or a periodic interrupt. The user can do one of the following:

- 1) Enable the interrupt with the PIE bit;
- 2) Enable the SQW output pin with the SQWE bit;
- Enable both at the same time and the same rate; or
- 4) Enable neither.

Table 3 lists the periodic interrupt rates and the squarewave frequencies that can be chosen with the RS bits. These four read/write bits are not affected by RESET.

### DALLAS /////

#### **Control Register B**

BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0
SET	PIE	AIE	UIE	SQWE	DM	24/12	DSE

**Bit 7: SET.** When the SET bit is 0, the update transfer functions normally by advancing the counts once per second. When the SET bit is written to 1, any update transfer is inhibited, and the program can initialize the time and calendar bytes without an update occurring in the midst of initializing. Read cycles can be executed in a similar manner. SET is a read/write bit and is not affected by RESET or internal functions of the device.

**Bit 6: Periodic Interrupt Enable (PIE).** The PIE bit is a read/write bit that allows the periodic interrupt flag (PF) bit in Register C to drive the IRQ pin low. When the PIE bit is set to 1, periodic interrupts are generated by driving the IRQ pin low at a rate specified by the RS3–RS0 bits of Register A. A 0 in the PIE bit blocks the IRQ output from being driven by a periodic interrupt, but the PF bit is still set at the periodic rate. PIE is not modified by any internal device functions, but is cleared to 0 on RESET.

**Bit 5: Alarm Interrupt Enable (AIE).** This bit is a read/write bit that, when set to <u>1</u>, permits the alarm flag (AF) bit in Register C to assert IRQ. An alarm interrupt occurs for each second that the three time bytes equal the three alarm bytes, including a don't-care alarm code of binary 11XXXXXX. The AF bit does not initiate the IRQ signal when the AIE bit is set to 0. The internal functions of the device do not affect the AIE bit, but is cleared to 0 on RESET.

**Bit 4: Update-Ended Interrupt Enable (UIE).** This bit is a read/write bit that enables the update-end flag (UF) bit in Register C to assert IRQ. The RESET pin going low or the SET bit going high clears the UIE bit.

The internal functions of the <u>device</u> do not affect the UIE bit, but is cleared to 0 on RESET.

**Bit 3: Square-Wave Enable (SQWE).** When this bit is set to 1, a square-wave signal at the frequency set by the rate-selection bits RS3–RS0 is driven out on the SQW pin. When the SQWE bit is set to 0, the SQW pin is held low. SQWE is a read/write bit and is cleared by RESET. SQWE is low if disabled, and is high impedance when V<sub>CC</sub> is below V<sub>PF</sub>. SQWE is cleared to 0 on RESET.

**Bit 2: Data Mode (DM).** This bit indicates whether time and calendar information is in binary or BCD format. The DM bit is set by the program to the appropriate format and can be read as required. This bit is not modified by internal functions or RESET. A 1 in DM signifies binary data, while a 0 in DM specifies BCD data.

**Bit 1: 24/12.** The 24/12 control bit establishes the format of the hours byte. A 1 indicates the 24-hour mode and a 0 indicates the 12-hour mode. This bit is read/write and is not affected by internal functions or RESET.

**Bit 0: Daylight Saving Enable (DSE).** This bit is a read/write bit that enables two daylight saving adjustments when DSE is set to 1. On the first Sunday in April, the time increments from 1:59:59 AM to 3:00:00 AM. On the last Sunday in October when the time first reaches 1:59:59 AM, it changes to 1:00:00 AM. When DSE is enabled, the internal logic test for the first/last Sunday condition at midnight. If the DSE bit is not set when the test occurs, the daylight saving function does not operate correctly. These adjustments do not occur when the DSE bit is 0. This bit is not affected by internal functions or RESET.

MSB

BALLAS ////X///

#### **Control Register C**

LSB

BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0
IRQF	PF	AF	UF	0	0	0	0

**Bit 7: Interrupt Request Flag (IRQF).** This bit is set to 1 when any of the following are true:

PF = PIE = 1AF = AIE = 1UF = UIE = 1

Any time the IRQF bit is 1, the  $\overline{\text{IRQ}}$  pin is driven low. This bit can be cleared by reading Register C or with a RESET.

**Bit 6: Periodic Interrupt Flag (PF).** This bit is readonly and is set to 1 when an edge is detected on the selected tap of the divider chain. The RS3 through RS0 bits establish the periodic rate. PF is set to 1 independent of the state of the PIE bit. When both PF and PIE are 1s, the IRQ signal is active and sets the IRQF bit. This bit can be cleared by reading Register C or with a RESET.

Bit 5: Alarm Interrupt Flag (AF). A 1 in the AF bit indi-
cates that the current time has matched the alarm time.
If the AIE bit is also 1, the IRQ pin goes low and a 1
appears in the IRQF bit. This bit can be cleared by
reading Register C or with a RESET.

**Bit 5: Update-Ended Interrupt Flag (UF).** This bit is set after each update cycle. When the UIE bit is set to 1, the 1 in <u>UF</u> causes the IRQF bit to be a 1, which asserts the IRQ pin. This bit can be cleared by reading Register C or with a RESET.

**Bits 3 to 0: Unused.** These bits are unused in Register C. These bits always read 0 and cannot be written.

#### **Control Register D**

LSB

MSB	
-----	--

MSB

BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0
VRT	0	0	0	0	0	0	0

**Bit 7: Valid RAM and Time (VRT).** This bit indicates the condition of the battery connected to the V<sub>BAT</sub> pin. This bit is not writeable and should always be 1 when read. If a 0 is ever present, an exhausted internal lithium energy source is indicated and both the contents of

the RTC data and RAM data are questionable. This bit is unaffected by RESET.

**Bits 6 to 0: Unused.** The remaining bits of Register D are not usable. They cannot be written and they always read 0.

# 

#### Century Register (DS12C887/DS12C887A Only)

The century register at location 32h is a BCD register designed to automatically load the BCD value 20 as the year register changes from 99 to 00. The MSB of this register is not affected when the load of 20 occurs, and remains at the value written by the user.

#### Nonvolatile RAM (NV RAM)

The general-purpose NV RAM bytes are not dedicated to any special function within the device. They can be used by the processor program as battery-backed memory and are fully available during the update cycle.

#### Interrupts

The RTC family includes three separate, fully automatic sources of interrupt for a processor. The alarm interrupt can be programmed to occur at rates from once per second to once per day. The periodic interrupt can be selected for rates from 500ms to 122µs. The update-ended interrupt can be used to indicate to the program that an update cycle is complete. Each of these independent interrupt conditions is described in greater detail in other sections of this text.

The processor program can select which interrupts, if any, are to be used. Three bits in Register B enable the interrupts. Writing a logic 1 to an interrupt-enable bit permits that interrupt to be initiated when the event occurs. A 0 in an interrupt-enable bit prohibits the IRQ pin from being asserted from that interrupt condition. If an interrupt flag is already set when an interrupt is enabled, IRQ is immediately set at an active level, although the interrupt initiating the event may have occurred earlier. As a result, there are cases where the program should clear such earlier initiated interrupts before first enabling new interrupts.

When an interrupt event occurs, the relating flag bit is set to logic 1 in Register C. These flag bits are set independent of the state of the corresponding enable bit in Register B. The flag bit can be used in a polling mode without enabling the corresponding enable bits. The interrupt flag bit is a status bit that software can interrogate as necessary. When a flag is set, an indication is given to software that an interrupt event has occurred since the flag bit was last read; however, care should be taken when using the flag bits as they are cleared each time Register C is read. Double latching is included with Register C so that bits that are set remain stable throughout the read cycle. All bits that are set (high) are cleared when read, and new interrupts that are pending during the read cycle are held until after the cycle is completed. One, two, or three bits can be set

when reading Register C. Each used flag bit should be examined when Register C is read to ensure that no interrupts are lost.

The second flag bit method is used with fully enabled interrupts. When an interrupt flag bit is set and the corresponding interrupt-enable bit is also set, the  $\overline{IRQ}$  pin is asserted low.  $\overline{IRQ}$  is asserted as long as at least one of the three interrupt sources has its flag and enable bits set. The IRQF bit in Register C is a 1 whenever the  $\overline{IRQ}$  pin is driven low. Determination that the RTC initiated an interrupt is accomplished by reading Register C. A logic 1 in bit 7 (IRQF bit) indicates that one or more interrupts have been initiated by the device. The act of reading Register C clears all active flag bits and the IRQF bit.

#### **Oscillator Control Bits**

When the DS12887, DS12887A, DS12C887, and DS12C887A are shipped from the factory, the internal oscillator is turned off. This prevents the lithium energy cell from being used until the device is installed in a system.

A pattern of 010 in bits 4 to 6 of Register A turns the oscillator on and enables the countdown chain. A pattern of 11x (DV2 = 1, DV1 = 1, DV0 = X) turns the oscillator on, but holds the countdown chain of the oscillator in reset. All other combinations of bits 4 to 6 keep the oscillator off.

#### Square-Wave Output Selection

Thirteen of the 15 divider taps are made available to a 1of-16 multiplexer, as shown in the functional diagram. The square-wave and periodic-interrupt generators share the output of the multiplexer. The RSO–RS3 bits in Register A establish the output frequency of the multiplexer (see Table 1). Once the frequency is selected, the output of the SQW pin can be turned on and off under program control with the square-wave enable bit, SQWE.

### **Periodic Interrupt Selection**

The periodic interrupt causes the IRQ pin to go to an active state from once every 500ms to once every 122µs. This function is separate from the alarm interrupt, which can be output from once per second to once per day. The periodic interrupt rate is selected using the same Register A bits that select the square-wave frequency (Table 1). Changing the Register A bits affects the square-wave frequency and the periodic-interrupt output. However, each function has a separate enable bit in Register B. The SQWE bit controls the square-wave output. Similarly, the PIE bit in Register B enables the periodic interrupt. The periodic interrupt can be used with software counters to measure inputs, create output intervals, or await the next needed software function.



	SELEC REGIS	T BITS		t <sub>PI</sub> PERIODIC INTERRUPT	SQW OUTPUT FREQUENCY
RS3	RS2	RS1	RS0	RATE	THEQUENCY
0	0	0	0	None	None
0	0	0	1	3.90625ms	256Hz
0	0	1	0	7.8125ms	128Hz
0	0	1	1	122.070µs	8.192kHz
0	1	0	0	244.141µs	4.096kHz
0	1	0	1	488.281µs	2.048kHz
0	1	1	0	976.5625µs	1.024kHz
0	1	1	1	1.953125ms	512Hz
1	0	0	0	3.90625ms	256Hz
1	0	0	1	7.8125ms	128Hz
1	0	1	0	15.625ms	64Hz
1	0	1	1	31.25ms	32Hz
1	1	0	0	62.5ms	16Hz
1	1	0	1	125ms	8Hz
1	1	1	0	250ms	4Hz
1	1	1	1	500ms	2Hz

# Table 3. Periodic Interrupt Rate andSquare-Wave Output Frequency

#### **Update Cycle**

The device executes an update cycle once per second regardless of the SET bit in Register B. When the SET bit in Register B is set to 1, the user copy of the doublebuffered time, calendar, and alarm bytes is frozen and does not update as the time increments. However, the time countdown chain continues to update the internal copy of the buffer. This feature allows time to maintain accuracy independent of reading or writing the time, calendar, and alarm buffers, and also guarantees that time and calendar information is consistent. The update cycle also compares each alarm byte with the corre-

sponding time byte and issues an alarm if a match or if a don't-care code is present in all three positions.

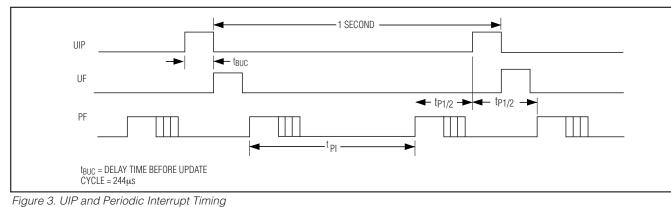
There are three methods that can handle RTC access that avoid any possibility of accessing inconsistent time and calendar data. The first method uses the updateended interrupt. If enabled, an interrupt occurs after every update cycle that indicates over 999ms is available to read valid time and date information. If this interrupt is used, the IRQF bit in Register C should be cleared before leaving the interrupt routine.

A second method uses the update-in-progress bit (UIP) in Register A to determine if the update cycle is in progress. The UIP bit pulses once per second. After the UIP bit goes high, the update transfer occurs 244µs later. If a low is read on the UIP bit, the user has at least 244µs before the time/calendar data is changed. Therefore, the user should avoid interrupt service routines that would cause the time needed to read valid time/calendar data to exceed 244µs.

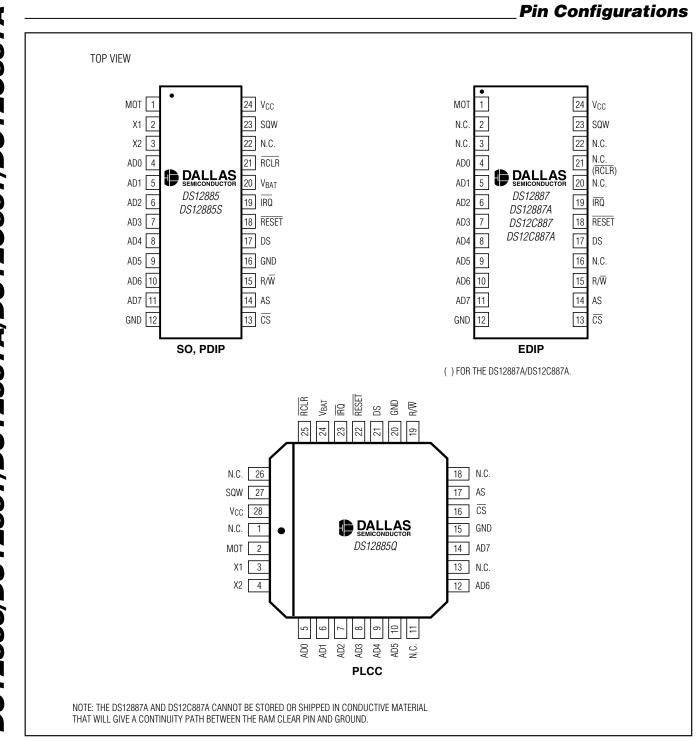
The third method uses a periodic interrupt to determine if an update cycle is in progress. The UIP bit in Register A is set high between the setting of the PF bit in Register C (Figure 3). Periodic interrupts that occur at a rate greater than t<sub>BUC</sub> allow valid time and date information to be reached at each occurrence of the periodic interrupt. The reads should be complete within one (t<sub>PI/2</sub> + t<sub>BUC</sub>) to ensure that data is not read during the update cycle.

### Handling, PC Board Layout, \_\_\_\_\_and Assembly

The EDIP module can be successfully processed through conventional wave-soldering techniques so long as temperature exposure to the lithium energy source does not exceed +85°C. Post-solder cleaning with waterwashing techniques is acceptable, provided that ultrasonic vibration is not used. Such cleaning can damage the crystal.



19



DS12885/DS12887/DS12887A/DS12C887/DS12C887A

BALLAS / XI/XI/VI

# Ordering Information

PART	TEMP RANGE	PIN- PACKAGE	TOP MARK*
DS12885	0°C to +70°C	24 PDIP	DS12885
DS12885N	-40°C to +85°C	24 PDIP	DS12885N
DS12885Q	0°C to +70°C	28 PLCC	DS12885Q
DS12885Q+	0°C to +70°C	28 PLCC	DS12885Q
DS12885QN	-40°C to +85°C	28 PLCC	DS12885Q
DS12885QN+	-40°C to +85°C	28 PLCC	DS12885Q
DS12885S	0°C to +70°C	24 SO (300 mils)	DS12885S
DS12885S+	0°C to +70°C	24 SO (300 mils)	DS12885S
DS12885SN	-40°C to +85°C	24 SO (300 mils)	DS12885S
DS12885SN+	-40°C to +85°C	24 SO (300 mils)	DS12885S
DS12885T	0°C to +70°C	32 TQFP	DS12885T
DS12885TN	-40°C to +85°C	32 TQFP	DS12885T
DS12887	0°C to +70°C	24 EDIP	DS12887
DS12887A	0°C to +70°C	24 EDIP	DS12887A
DS12887A+	0°C to +70°C	24 EDIP	DS12887A
DS12C887	0°C to +70°C	24 EDIP	DS12C887
DS12C887A	0°C to +70°C	24 EDIP	DS12C887
DS12C887A+	0°C to +70°C	24 EDIP	DS12C887

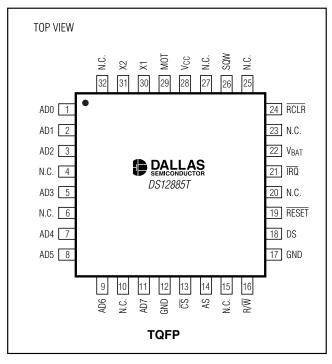
+Denotes a lead-free/RoHS-compliant device.

\*A "+" anywhere on the top mark indicates a lead-free device, and an "N" indicates an industrial temperature range device.

### \_Chip Information

TRANSISTOR COUNT: 17,000 PROCESS: CMOS SUBSTRATE CONNECTED TO GROUND





### **Thermal Information**

PACKAGE	THETA-JA (°C/W)	THETA-JC (°C/W)
PDIP	75	30
SO	105	22
PLCC	95	25



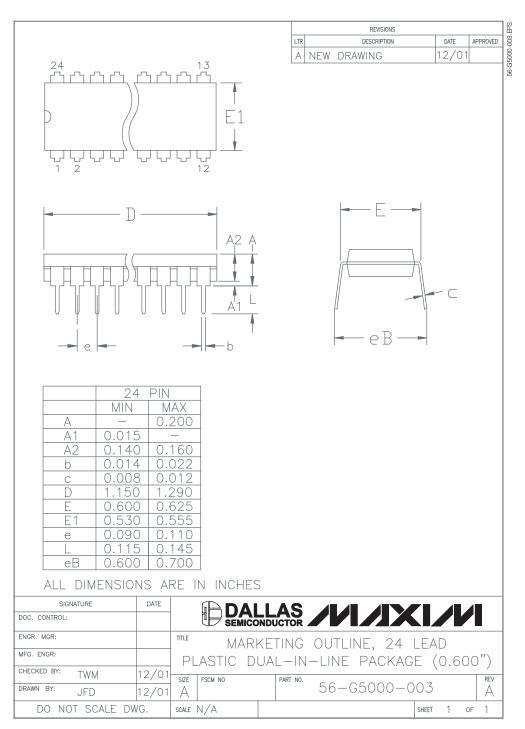
#### REVISIONS Ν LTR DESCRIPTION DATE APPROVED е А NEW DRAWING 5/18 J.W. B INC. ECN NO. 8680 E1 Н D Α2 А L A1 LTR MIN MAX IN. 0.094 0.105 А MM 2.39 2.67 IN 0.004 0.012 A1 MM 0.102 0.30 IN. 0.089 0.095 A2 MM 2.26 2.41 0.020 IN. 0.013 b ΜМ 0.33 0.51 0.013 IN. 0.009 20 PIN 24 PIN 28 PIN 16 PIN 18 PIN С MM 0.229 0.33 MIN MAX MIN MAX MIN MAX MIN MAX MIN MAX 0.598 0.612 IN. 0.398 0.412 0.448 0.462 0.498 0.511 0.698 0.712 D MM 10.11 10.46 11.38 11.73 12.65 12.99 15.19 15.54 17.73 18.08 IN. .050 BSC е MM 1.27 BSC 0.290 0.300 IN THE CHAMFER ON THE BODY IS OPTIONAL. E1 MM 7.37 7.62 IF IT IS NOT PRESENT, A TERMINAL 1 IDENTIFIER IN. 0.398 0.416 MUST BE POSITIONED SO THAT 1/2 OR MORE OF Н MM 10.11 10.57 IT'S AREA IS CONTAINED IN THE HATCHED ZONE. 0.040 0.016 IN. L ΜМ 0.40 1.02 0° 8° Θ DATE SIGNATURE E ///XI//I DOC. CONTROL: J.WILKINS 5/94 ENGR. MGR: 5/94 TITLE **B.W.MCARTY** PACKAGE OUTLINE .300" SOIC 16,18,20,24&28 LD. MFG. ENGR: C.M.SELLS 5/94 CHECKED BY: C.M.SELLS 5/94 SIZE FSCM NO PART NO. REV 56-G4009-001 DRAWN BY: M.W.C. В 5/94 А DO NOT SCALE DWG. SCALE N/A SHEET 1 OF 1

For the latest package outline information, go to www.maxim-ic.com/DallasPackInfo

Package Information

### **Package Information (continued)**

For the latest package outline information, go to www.maxim-ic.com/DallasPackInfo.



### **Package Information (continued)**

For the latest package outline information, go to www.maxim-ic.com/DallasPackInfo.

REVISIONS -001 LTR DESCRIPTION DATE APPROVED ECN 35439 56-G0001 А Some pins may be missing by design 1 F DIMENSIONS ARE IN INCHES. See page 2 for dimensions in mm AΙ 28 PIN 32 PIN 740 24 PIN 40 PIN 720 МАХ MAX MIN MAX МАХ MIN MTN MIN 1.540 2.115 А 1.320 1.340 1.520 1.680 1.720 2.075 С 0.330 0.370 0.330 0.370 0.330 0.370 0.280 0.320  $\mathbb{D}$ 0.100 0.130 0.100 0.130 0.070 0.100 0.070 0.100 MIN MAX В 0.68 0.72 24 PIN 720, 28 PIN 720 and 40 PIN 720 В 0.720 0.740 24 PIN 740, 28 PIN 740 and 32 PIN 740 ALL PACKAGES MIN MAX 0.040 E F 0.120 0.160 0.090 G 0.110 Н 0.590 0.630 J 0.008 0.012 К 0.015 0.021 SIGNATURE DATE DALLAS SEMICONDUCTOR DOC. CONTROL: ENGR. MGR TITLE Marketing Outline MFG. ENGR: Encapsulated DIP Package CHECKED BY: SIZE FSCM NO DWG NO. REV 56-G0001-001 DRAWN BY: А 2/03 А RMA 2 N/A SHEET OF DIP\_ModulesIC.SLDDRW SCALE

DALLAS JUI JXIJU

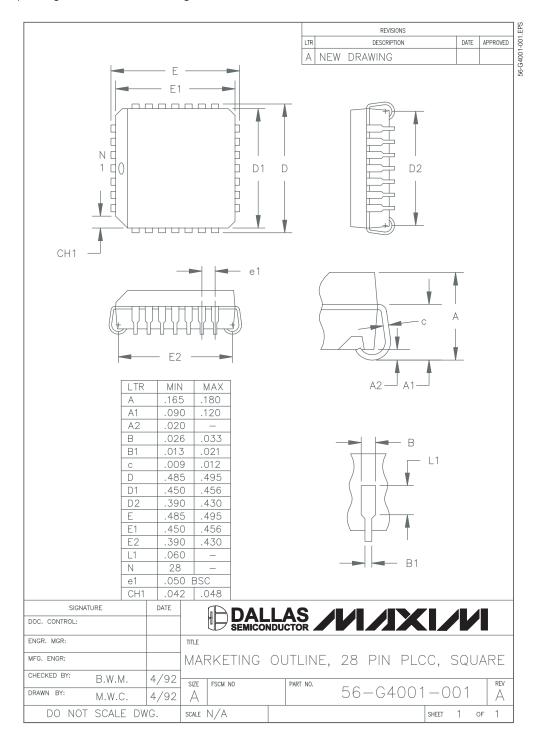
### **Package Information (continued)**

For the latest package outline information, go to www.maxim-ic.com/DallasPackInfo.

				LITD		REVISIONS		DATE	APPROVED
				LTR		DESCRIPTION		DATE	APPROVED
				ALE	CN 3543	37			
ALL DIME	ENSIONS AF	RE IN MM							
	24 PIN	28			PIN 740		PIN 720		
MI		MIN	MAX	MIN	MAX	MIN	MAX	_	
	. <u>53 34.04</u> 38 9.40		<u>39.12</u> 9.40	42.67 8.38	<u>43.69</u> 9,40	52.71 7.11	53.72 8.13	-	
	54 3.30		3.30	1.78	2.54	1,78	2.54	-	
		MAX							
B		<u>18.29 24</u>	PIN 720 PIN 740	) <u>, 28 PIN</u>	<u>  720 ar</u>	nd 40 PI	N 720		
D	10,67	18,80 24	F1N /40	), <u>co fi</u> i	<u>1740 ur</u>	<u>10 36 FI</u>	<u>IN 740</u>		
		ALL PA	CKAGES						
		MIN	MAX						
	E		1.02						
	G		2,79						
	 H		16.00						
			0.30						
	K	0.38	0.53						
									5.5.
		SIZE FSCM NO		DWG NO.	56-0		101		REV
		SIZE FSCM NO A SCALE N/6		DWG NO.	56-0	i0001-0	)01	2	A

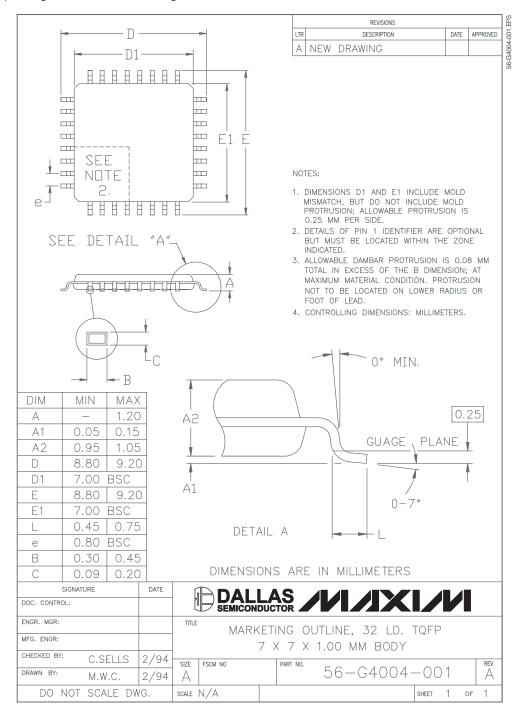
### **Package Information (continued)**

For the latest package outline information, go to www.maxim-ic.com/DallasPackInfo.



#### **Package Information (continued)**

For the latest package outline information, go to www.maxim-ic.com/DallasPackInfo



Maxim cannot assume responsibility for use of any circuitry other than circuitry entirely embodied in a Maxim product. No circuit patent licenses are implied. Maxim reserves the right to change the circuitry and specifications without notice at any time.

#### Maxim Integrated Products, 120 San Gabriel Drive, Sunnyvale, CA 94086 408-737-7600

© 2006 Maxim Integrated Products

Printed USA **MAXIM** is a registered trademark of Maxim Integrated Products, Inc.

DALLAS is a registered trademark of Dallas Semiconductor Corporation.

27